EMC Optimized Buck Converter Layout

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Jens Hedrich – Senior FAE, Central Europe



2010 – Present

- MPS Senior FAE since 2010, working with industrial and automotive customers on power supply design.
- Particular specialty focus on layout and EMC topics, including frequently visiting automotive EMC lab for EVB testing / optimization and improving MPS automotive/industrial EVB's EMC performance

1999 – 2010 FAE at Linear Technology

 Support industrial and automotive customers; Support LTC's EMC clean EV-Board DC1212 (LT3480/LT3685)

1995 – 1998

 Hardware design engineer at Nokia Mobile Phones; Worked on early automotive Telematic solution with e-call and emergency battery; EMC support





The Motivation

Initial System Set-Up and PCB partitioning

Component Placement and Layer Stack

Copper Under the Inductor or Not: the Classic Debate

Example Case Study – How to improve EMC Performance

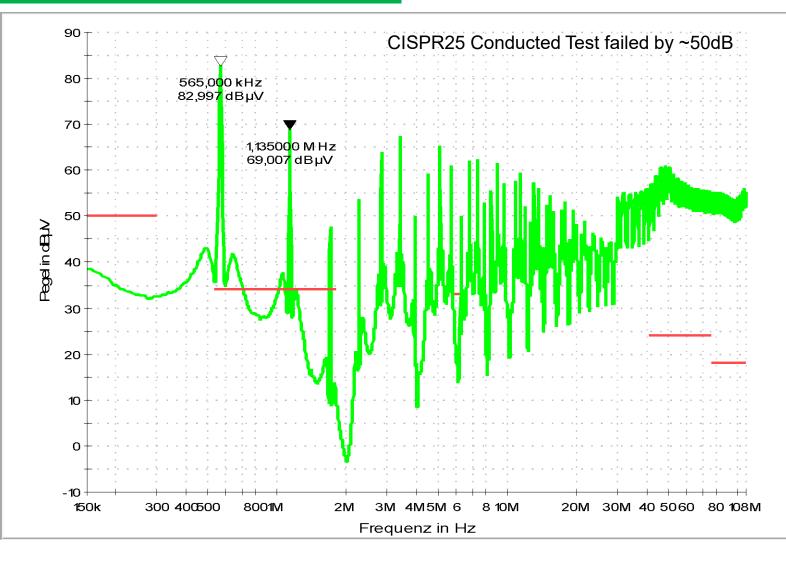
Frequently Asked Questions About Layout for EMI

Open Q&A



Our Motivation: Avoiding This Result

EMC Test Result of a Bad* PCB Without Filter



30V / 7A Sync. Buck Board Optimized for Thermal Performance but <u>not EMC</u>

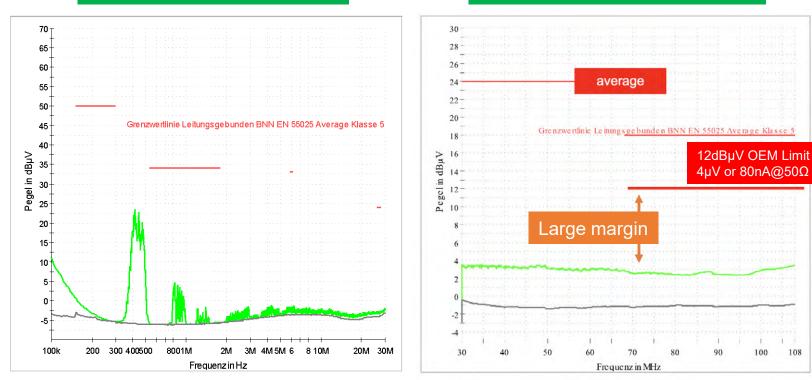


- Large SW area
- No solid GND plane
- Only two Layer
- NO EMC Filter



A Much, *Much* Better Board

100kHz to 30MHz 9kHz RBW



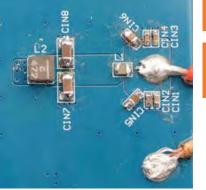
30MHz to 108MHz 120kHz RBW

EVQ4430-00A 480kHz Spread Spectrum



Learn how to get to this level

https://www.monolithicpower.com/en/support/webinars.html

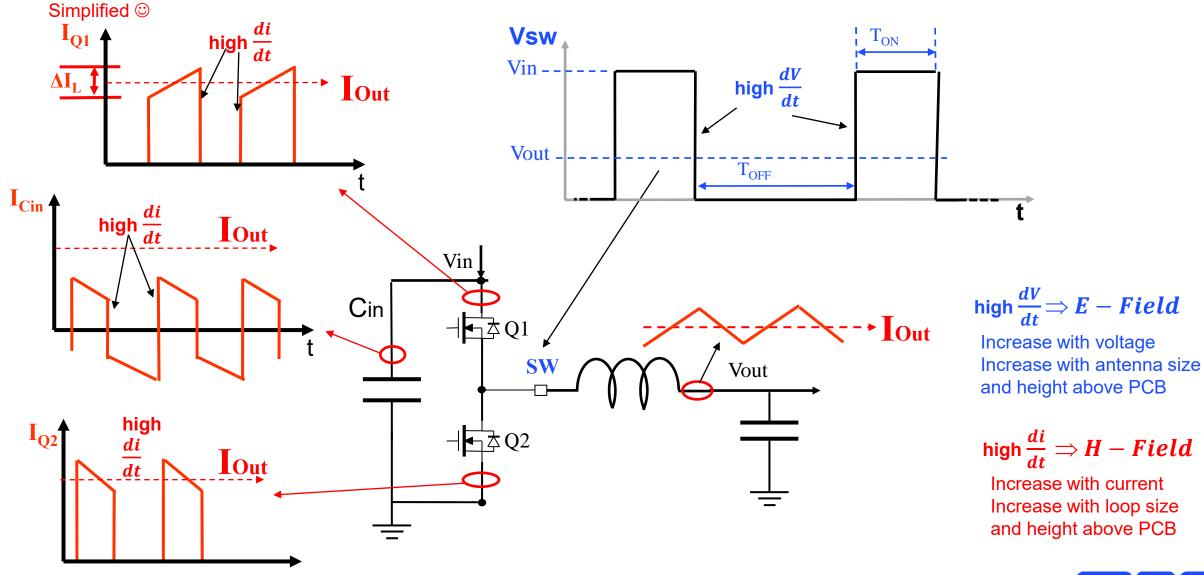


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Filter on bottom side

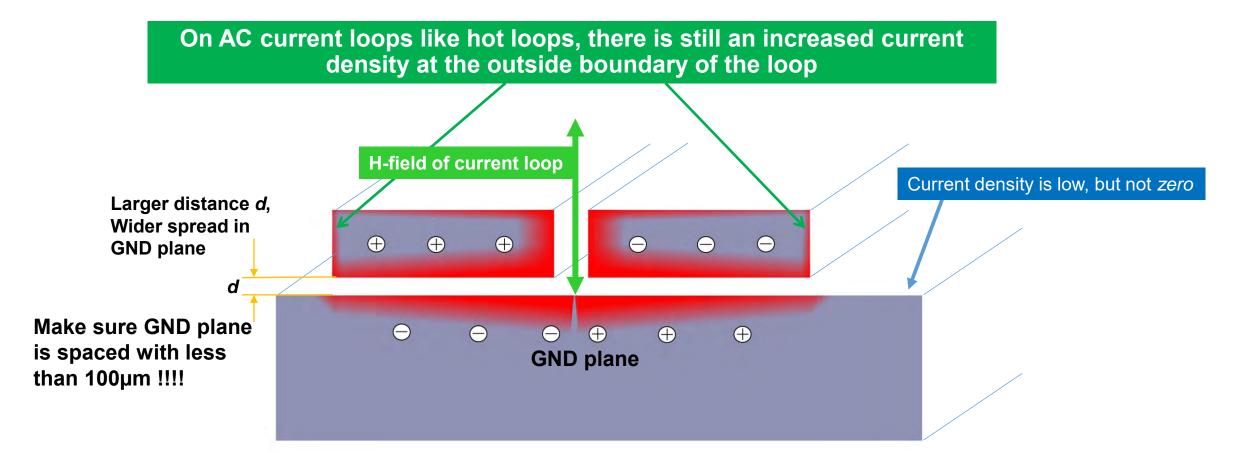
Two stage filter with small components

Refresh: Buck Converter Voltage and Current Waveforms



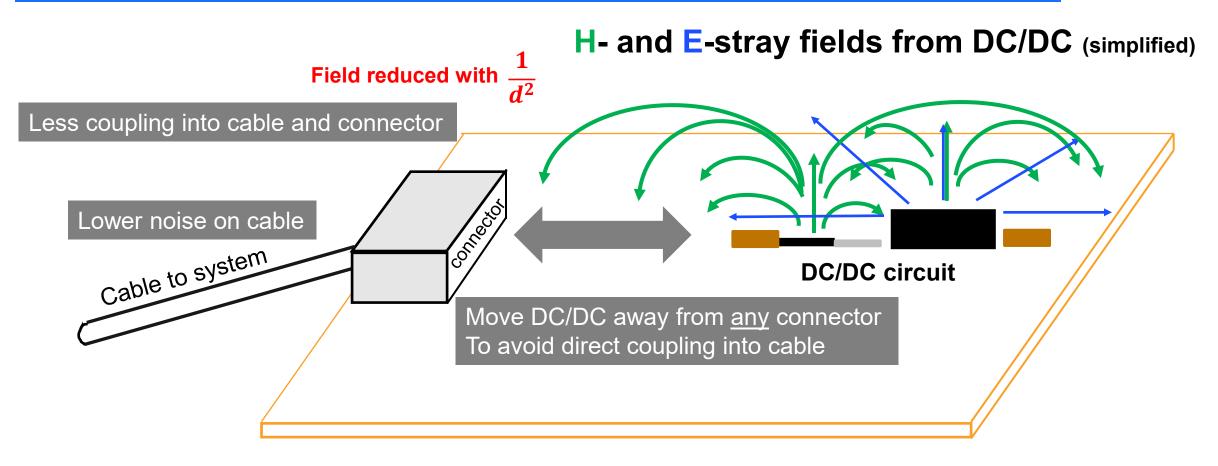
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Reminder From a Previous Webinar: Magnetic Antennas





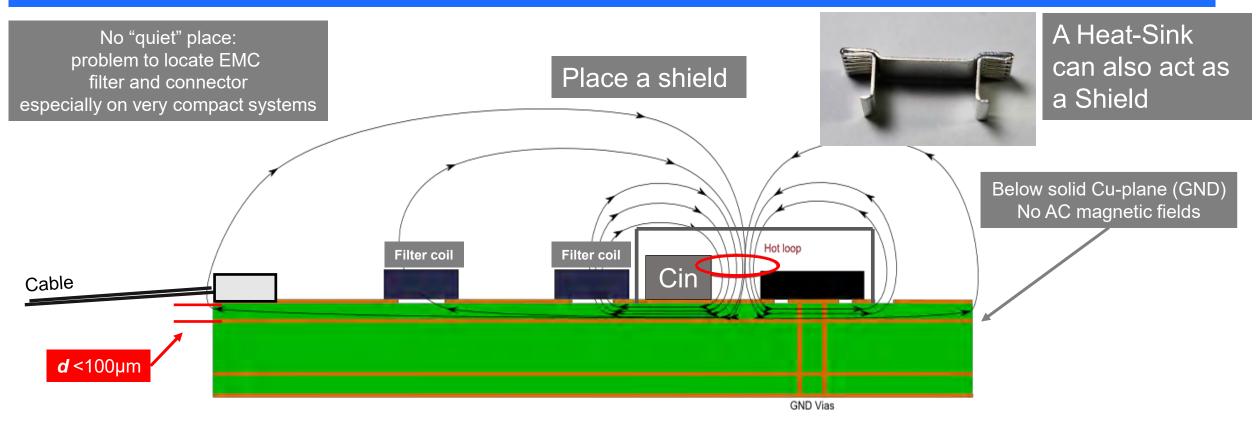
System Partitioning: Where to Place the DC/DC?



- EMC filter components must be placed close to connector
- In case of two side assembly, EMC filter on opposite side with respect to DC/DC Converter gives best results

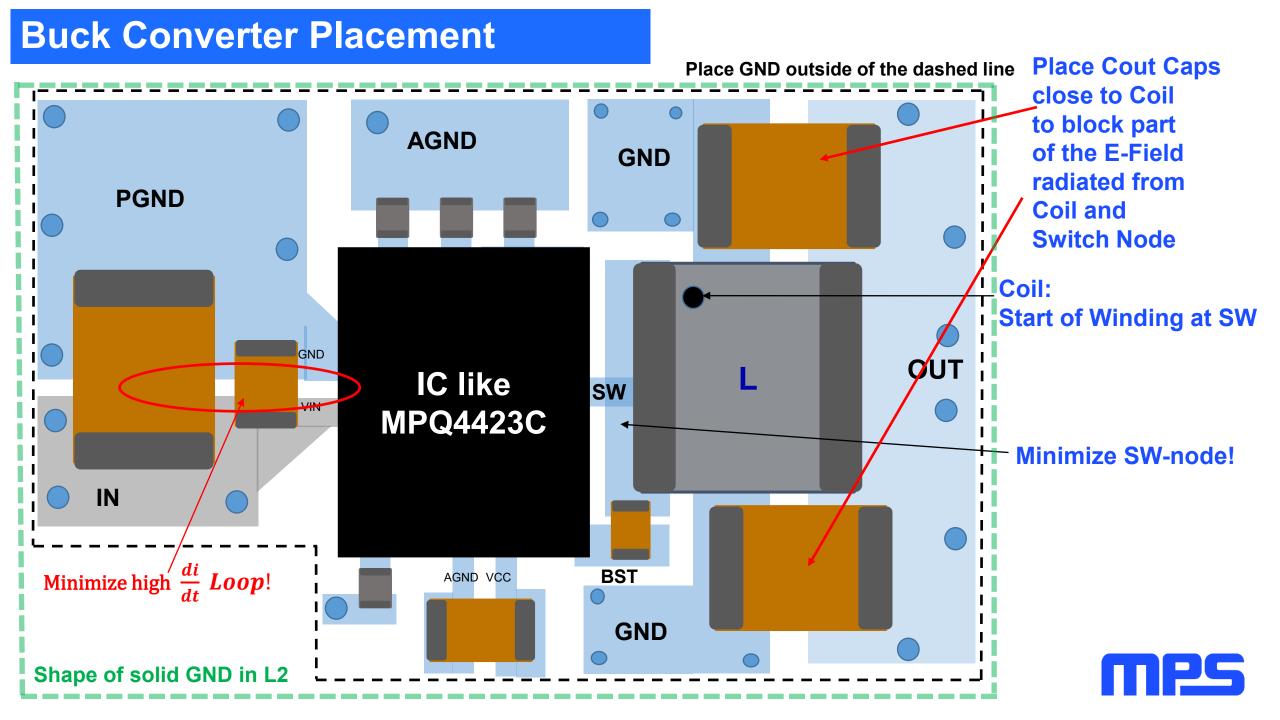


Coupling Into Other Circuits: Single Side Assembly

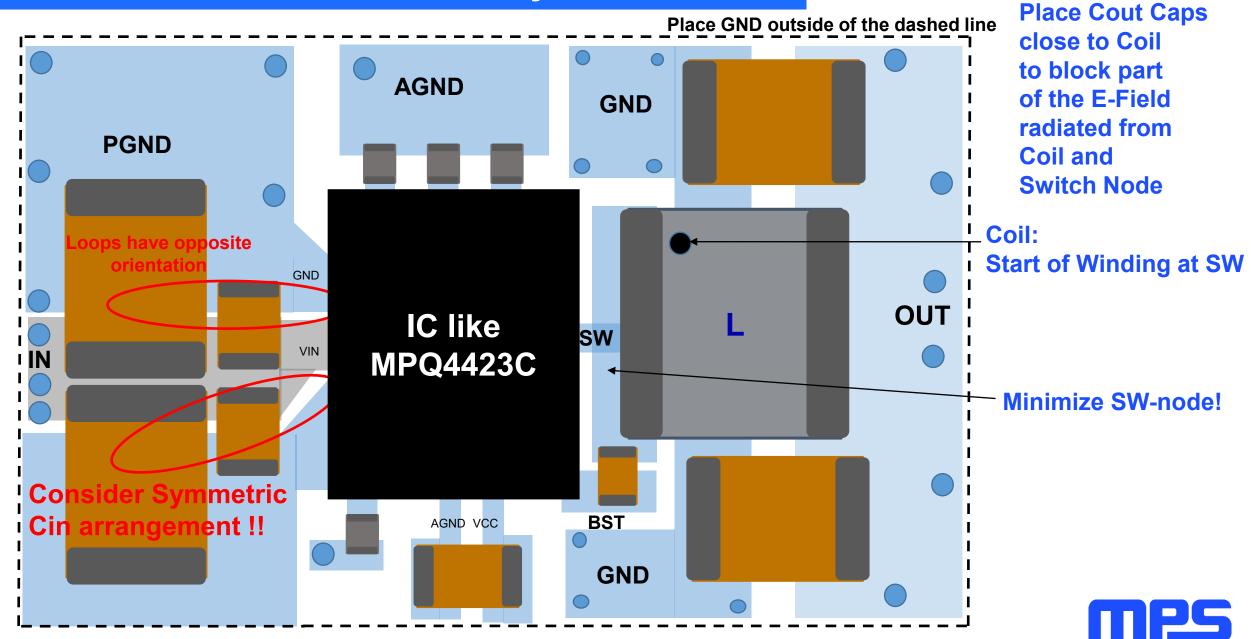


In case direct connection of housing, heatsink or shield is permitted

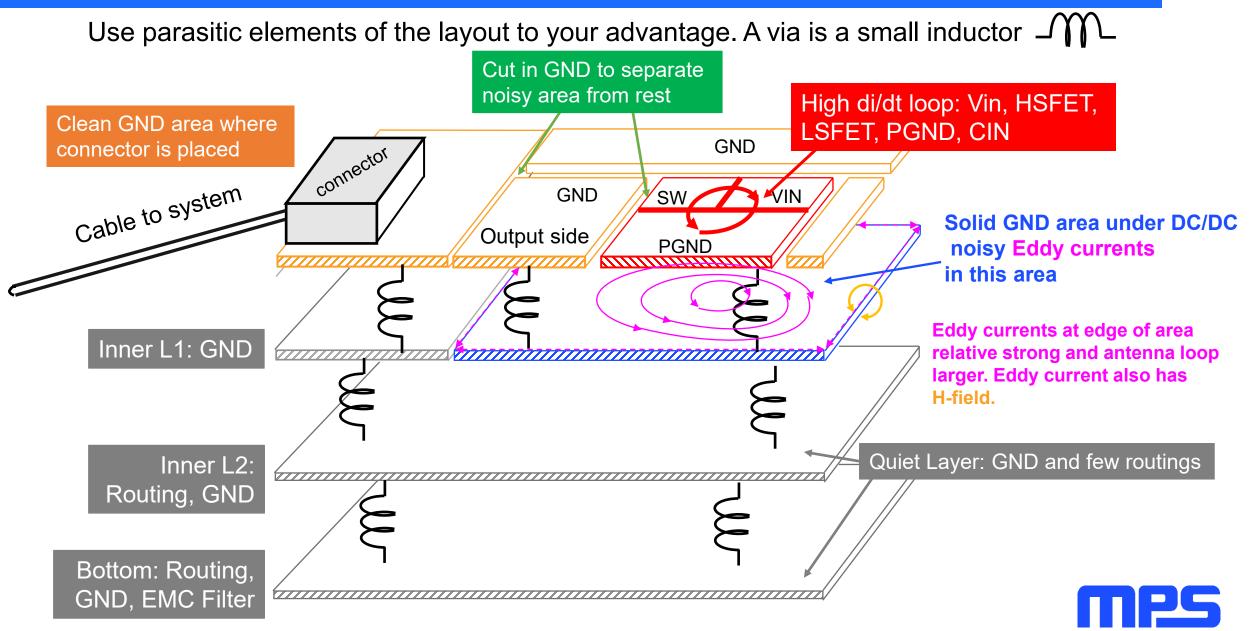
PCB-GND Floating metal heatsink or housing acts as antenna! Connection to Heatsink, Shield or housing 3x 0402 or 0603 MLCC capacitors, 100nF



Buck Converter Placement: Symmetric Cin



Look at the PCB In 3-Dimensions: Simplified Equivalent Representation



Opinion A:

"No! AC magnetic field from coil will create Eddy currents in copper under inductor. This will reduce effective inductance and create additional losses!"

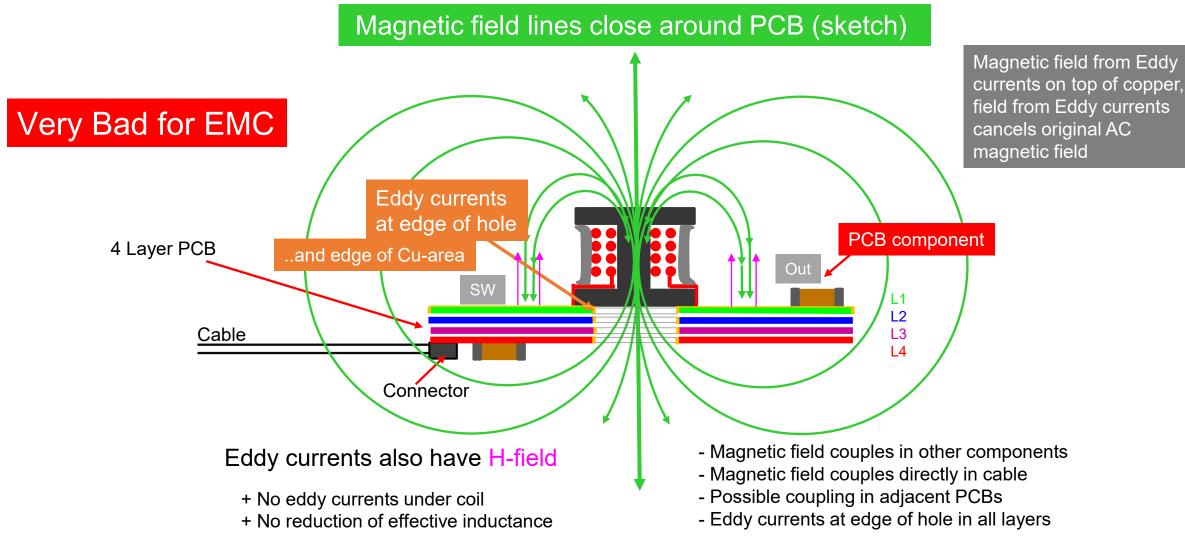
Opinion B:

"Yes! Directly on top side of PCB to avoid magnetic fields disturbing other layers of the PCB!"

Which opinion is right?

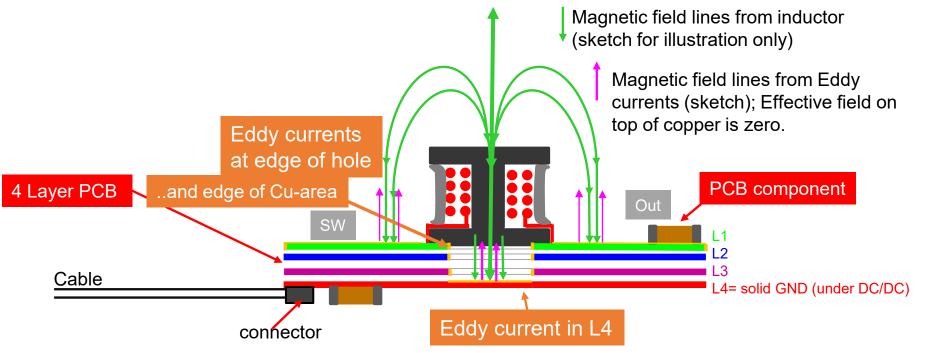


Example 1: No Copper Under Coil in all Layers



NO "quiet" position on PCB for EMC filter

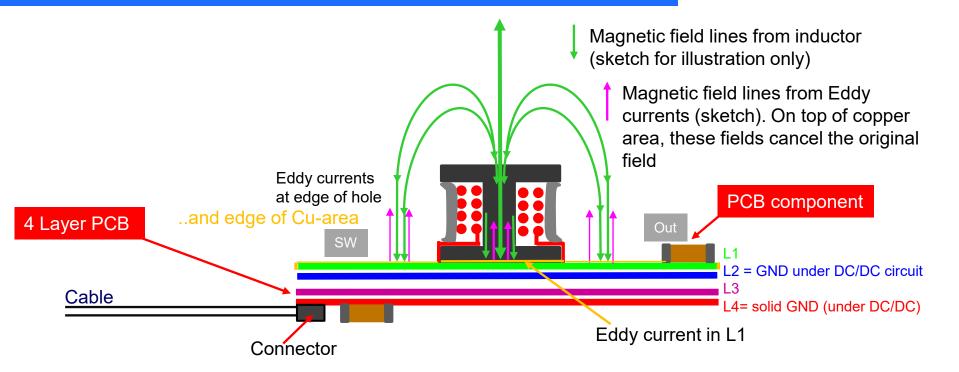
Example 2: Copper Under Coil in Layer 4



- ++ much lower magnetic field around PCB
- + less direct coupling into cable

- Losses in Cu due to Eddy currents
- Reduced effective inductance
- Eddy currents at edge of hole in L1-L3
- Bottom side of PCB much cleaner, but not completely clean
- Eddy currents flowing in L4 will create voltage drops across layer-impedance.
- Layer impedance is further increased by any holes or routings
- EMC filter components are referred to a noisy GND and therefore will not be fully effective

Example 3: Copper Under Coil in all Layers



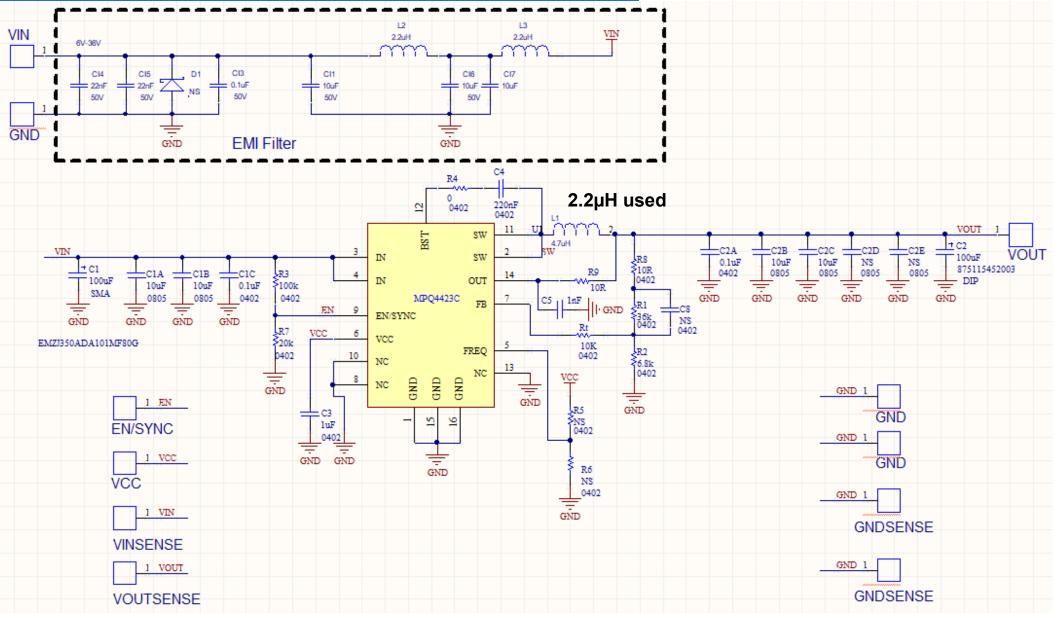
- + No AC magnetic field on bottom side of PCB
- + No magnetic coupling into bottom side components
- + Reduced Magnetic field coupling in cable
- + Reduced coupling in adjacent PCBs
- + AC Magnetic fields only on top side of PCB
- + inner layer should be clean
- Bottom side of PCB CLEAN
- EMC filter can be placed effectively here

- Losses in Cu due to Eddy currents
- Increased parasitic capacity of coil
- Reduced effective inductance
- Eddy currents under coil in L1 and at edge of Cu-area

Example Case: MPQ4423C Test EVB



Test EVQ4423C Schematic



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5A Buck Converter Example: MPQ4423C



T-EVQ4423C-L-00B Low Frequency CE

Test Procedere :	Conducted Emission
Test Standard :	CISPR25
Limit(s) :	OEM Spec
Frequency Range :	0.15kHz – 30MHz
Measurement Port :	Vbat
Detektor(s) :	Peak / Average
Input Voltage :	13.0V
Output Voltage :	3.3V
Output Current :	2.2A
Switchting Frequency :	400kHz with Spread Spectrum
Modifications :	
-	

Comment :









T-EVQ4423C- Coil Comparison

Test Procedere :	Conducted Emission
Test Standard :	CISPR25
Limit(s) :	OEM Spec
Frequency Range :	0.15kHz – 30MHz
Measurement Port :	Vbat
Detektor(s) :	Average
Input Voltage :	13.0V
Output Voltage :	3.3V
Output Current :	2.2A
Switchting Frequency :	400kHz with Spread Spectrum
Modifications :	

Comment :





T-EVQ4423C-L-00B - Comparison

Test Procedere :

Frequency Range :

Measurement Port: Vbat

13.0V

3.3V

2.2A

Test Standard :

Limit(s) :

Detektor(s) :

Input Voltage :

Output Voltage :

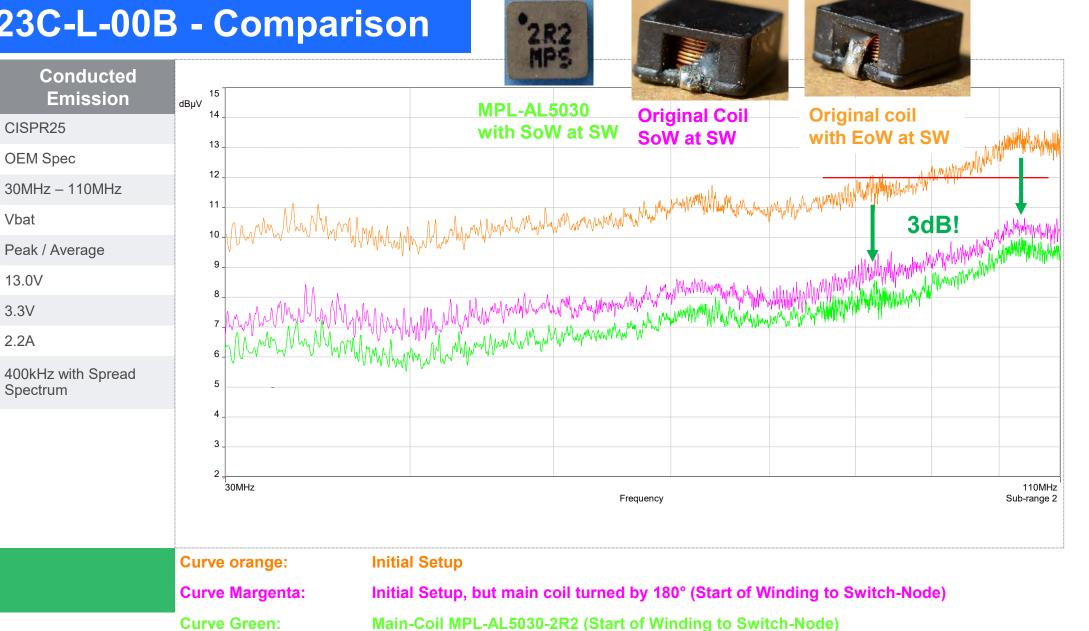
Output Current :

Switchting

Frequency :

Modifications :

Comment:



Modified Board

1st Modification Step:

- Reduce SW-node
- Reduce Vout
- Remove Vin, Vcc and Vout pins

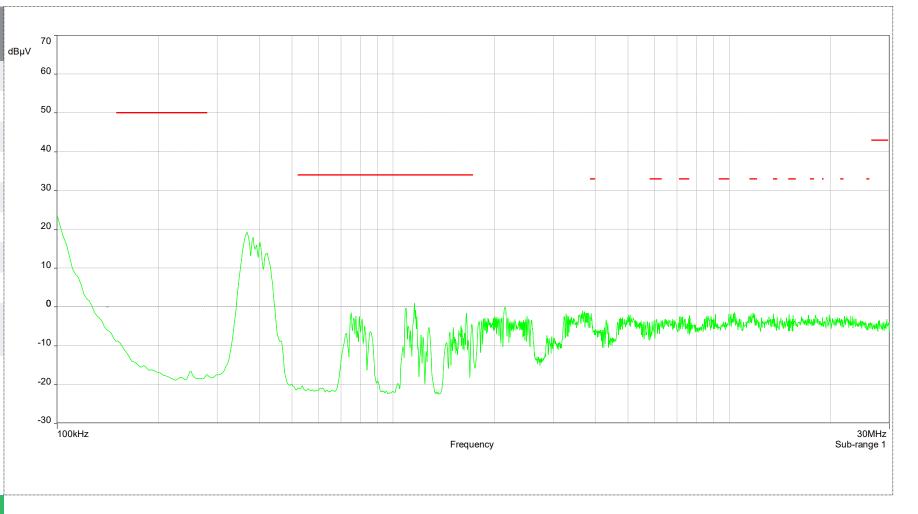


Test Procedere :	Conducted Emission
Test Standard :	CISPR25
Limit(s) :	OEM Spec
Frequency Range :	0.15kHz – 30MHz
Measurement Port :	Vbat
Detektor(s) :	Peak / Average
Input Voltage :	13.0V
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Switchting Frequency :	400kHz with Spread Spectrum
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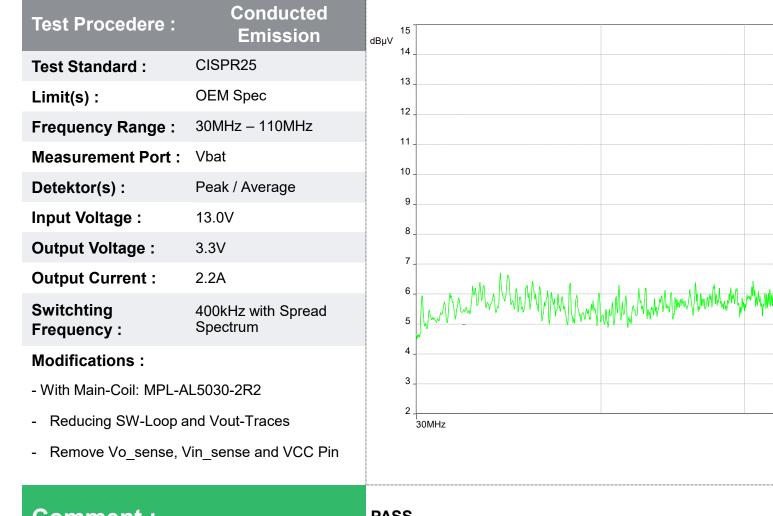
- Modifications :
- With Main-Coil: MPL-AL5030-2R2
- Reducing SW-Loop and Vout-Traces
- Remove Vo_sense, Vin_sense and VCC Pin

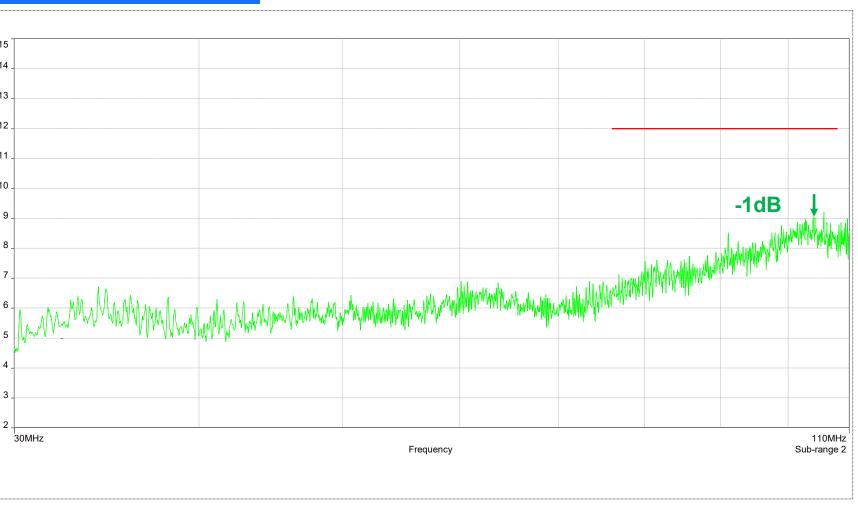
Comment :

PASS



mps





Comment :

PASS



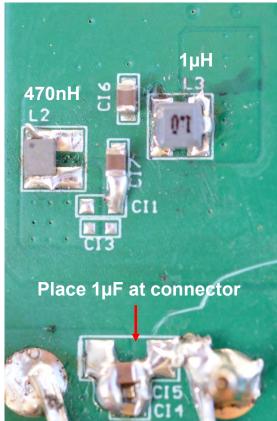
Modified Board

1st Modification Step:

- Reduce SW-node
- Reduce Vout
- Remove Vin, Vcc and Vout pins

2nd Modification Step:

- Place 1210 Cout next to Coil-
- Modify Input Filter AY3020-1µH and AT2512-470nH





T-EVQ4423C Modification Step 2 LF CE

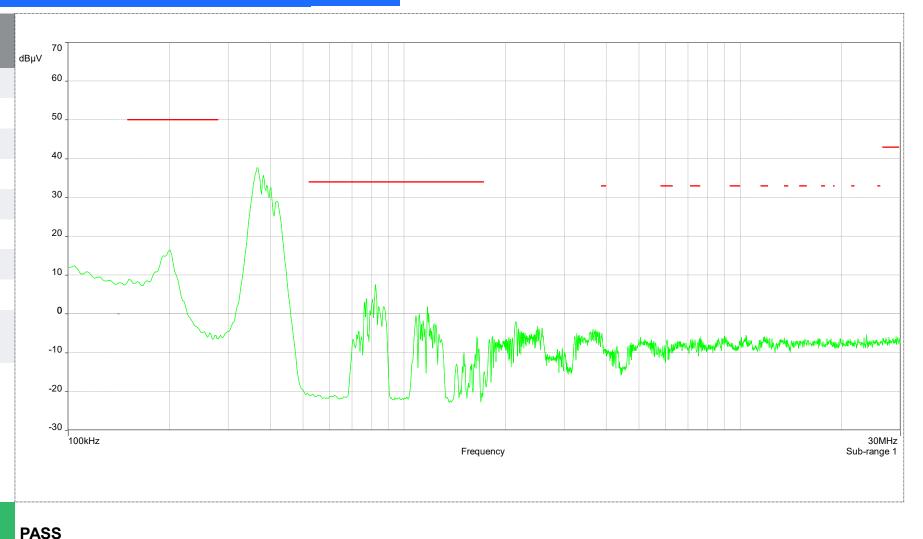
Test Procedere :	Conducted Emission
Test Standard :	CISPR25
Limit(s) :	OEM Spec
Frequency Range :	0.15kHz – 30MHz
Measurement Port :	Vbat
Detektor(s) :	Peak / Average
Input Voltage :	13.0V
Output Voltage :	3.3V
Output Current :	2.2A
Switchting Frequency :	400kHz with Spread Spectrum

Modifications :

- With Main-Coil: MPL-AL5030-2R2
- Reducing SW-Loop and Vout-Traces
- Remove Vo_sense, Vin_sense and VCC Pin
- Modify Input Filtering

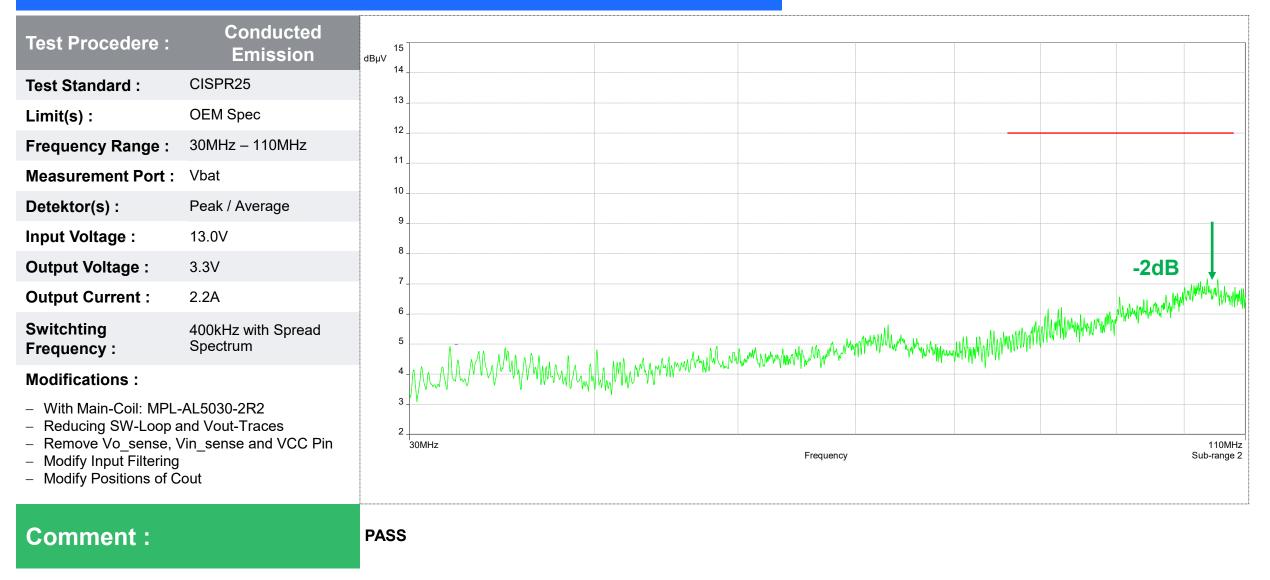
Comment :

- Modify Positions of Cout





T-EVQ4423C Modification Step 2 HF CE

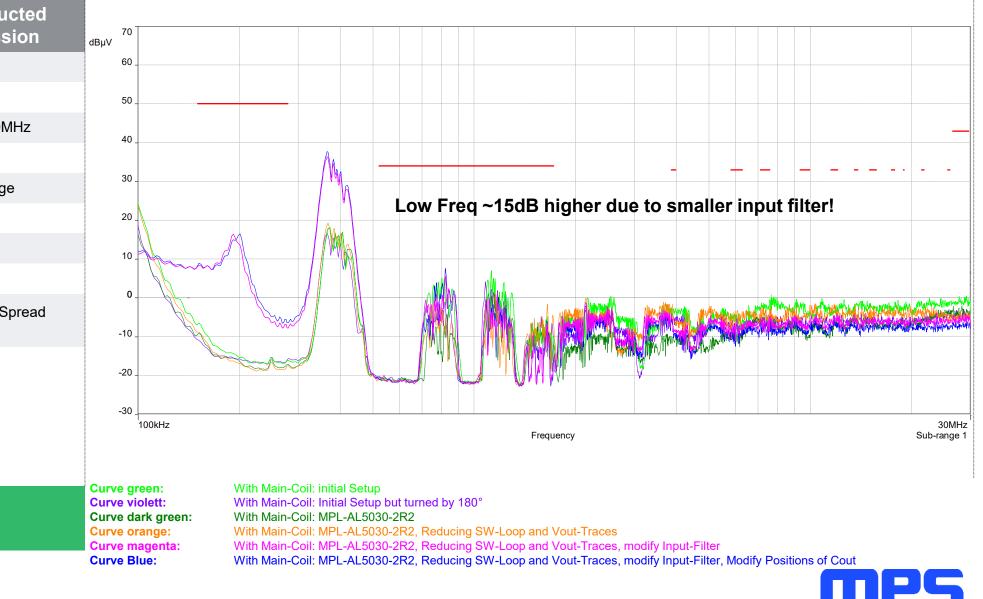




T-EVQ4423C Summary of Modifications

Test Procedere :	Conducted Emission
Test Standard :	CISPR25
Limit(s) :	OEM Spec
Frequency Range :	0.15kHz – 30MHz
Measurement Port :	Vbat
Detektor(s) :	Peak / Average
Input Voltage :	13.0V
Output Voltage :	3.3V
Output Current :	2.2A
Switchting Frequency :	400kHz with Spread Spectrum
Modifications :	

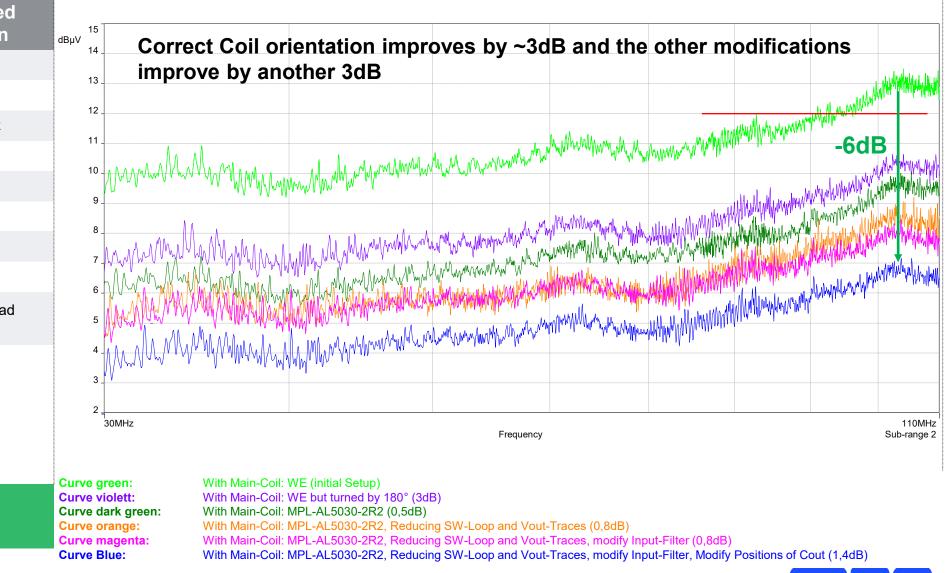
Comment :



T-EVQ4423C Summary of Modifications

Test Procedere :	Conducted Emission
Test Standard :	CISPR25
Limit(s) :	OEM Spec
Frequency Range :	30MHz – 110MHz
Measurement Port :	Vbat
Detektor(s) :	Peak / Average
Input Voltage :	13.0V
Output Voltage :	3.3V
Output Current :	2.2A
Switchting Frequency :	400kHz with Spread Spectrum
Modifications :	

Comment:

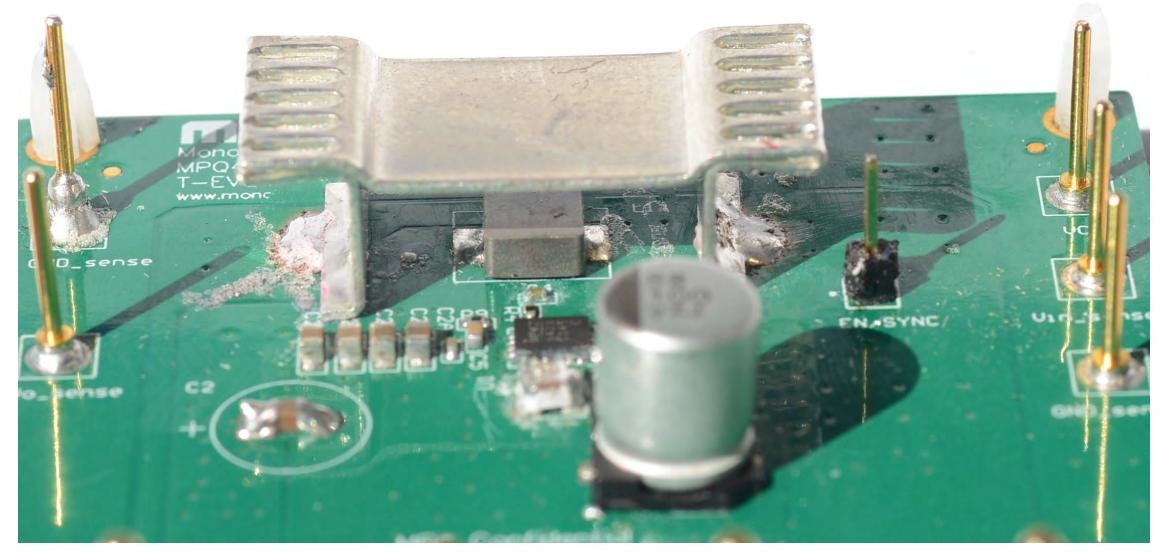


Extended Test: Use Fsw = 2MHz Unmodified Board – Only Coil with and without Shield/Heatsink

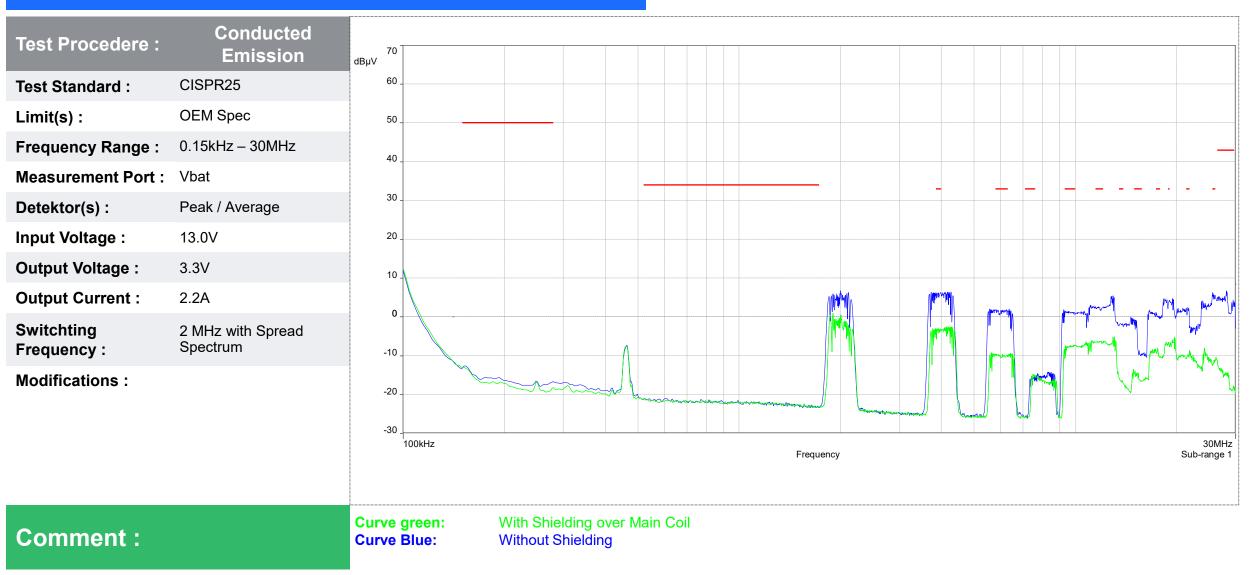


Heatsink as a Shield

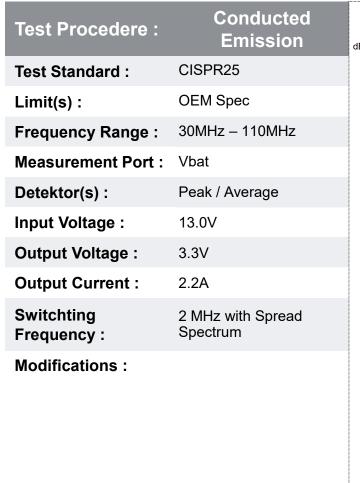
No need for a completely closed shield box for DC/DC EMC



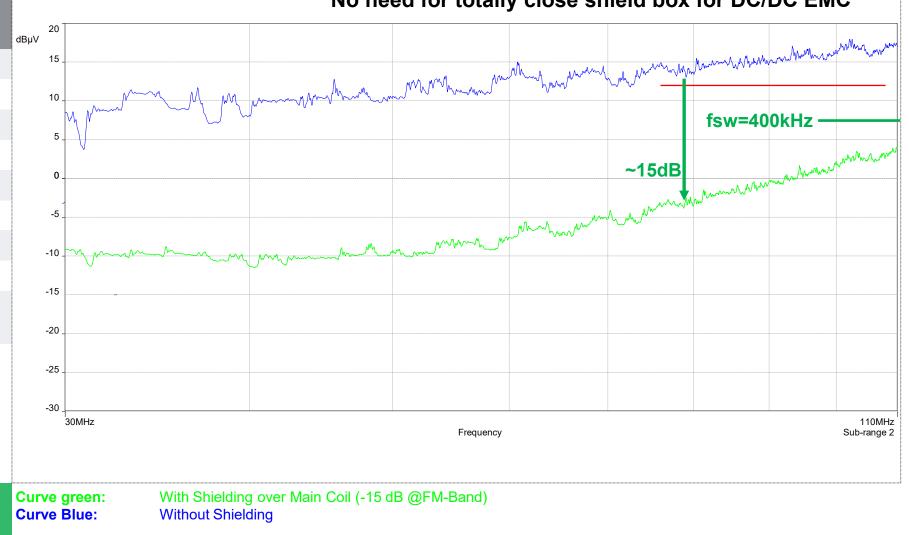




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Comment :

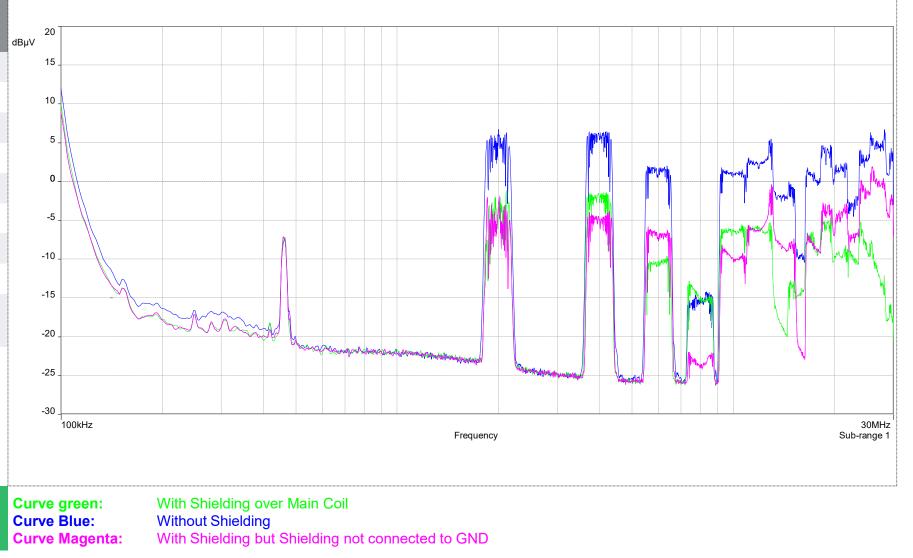




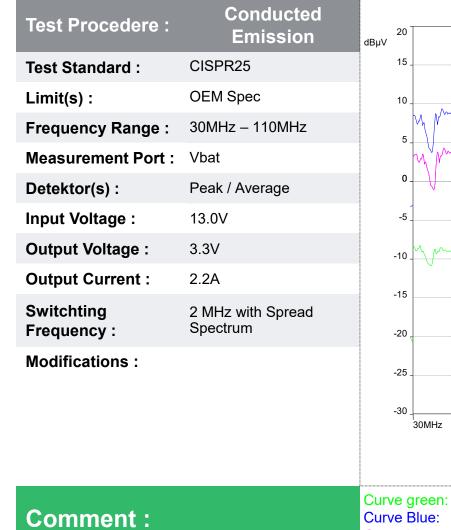


Test Procedere :	Conducted Emission	2 dBµV
Test Standard :	CISPR25	1
Limit(s) :	OEM Spec	1
Frequency Range :	0.15kHz – 30MHz	
Measurement Port :	Vbat	
Detektor(s) :	Peak / Average	
Input Voltage :	13.0V	-
Output Voltage :	3.3V	-1
Output Current :	2.2A	-1
Switchting Frequency :	2 MHz with Spread Spectrum	-1
Modifications :		-2
		-3

Comment :



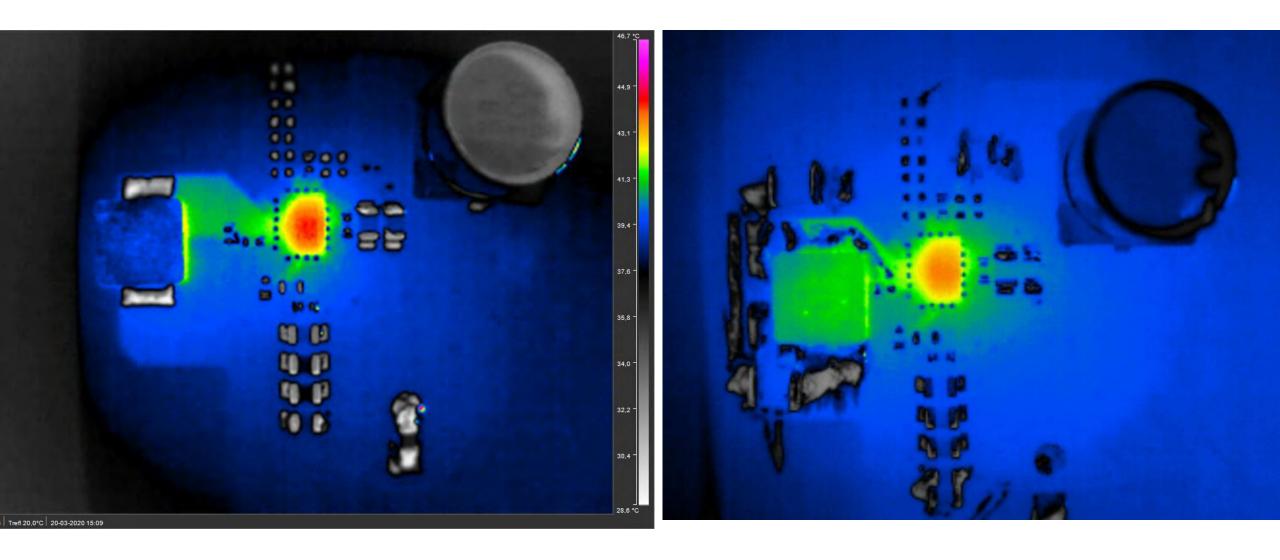
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Thermal Behaviour





NEW: Office & EMI Lab in Ettenheim/Germany (Opening Q2/2021)

EMC-Lab

Jan Spindler, EMC Lab Manager, strongly supported this Webinar!

SAC3 – Chamber

For Emission and Immunity Testing of Automotive, Industrial, and Consumer Electronics

CISPR25 – Chamber

For Emission and Immunity Testing of Automotive Electronics

Shielded – Chamber

For Conducted Emission and Immunity Testing of Automotive, Industrial, and Consumer Applications

Pulses and Application Engineering Modern Workplaces for Electrical Testing and Application Engineering





Some Frequently Asked Questions About Layout for EMC

- 1. Can I place the inductor on the opposite side of the PCB?
- 2. Can I place the input capacitors at the opposite side of the PCB?
- 3. Why Al-Elco at Vin?
- 4. Is there any difference in output filtering for buck and boost topology? How about 4 switch buck boost?
- 5. Shall I connect AGND and PGND at the power IC or somewhere else?
- 6. Can I connect my shield (Heat Sink) to a different potential like Vout or VLED+?
- 7. What to do with isolated copper islands?

